

SILICON N-CHANNEL DUAL GATE MOS-FET

Depletion type field-effect transistor in a metal TO-72 envelope with source and substrate connected to the case, intended for a wide range of v.h.f. applications, such as v.h.f. television tuners, f.m. tuners, as well as for applications in communication, instrumentation and control.

This MOS-FET tetrode is protected against excessive input voltage surges by integrated back-to-back diodes between gates and source.

The tetrode configuration, a series arrangement of two gate controlled channels, offers:

- very low feedback capacitance providing the possibility of more than 40 dB gain control in r.f. amplifiers requiring negligible a.g.c. power.
- excellent signal handling capability over the entire gain control range.
- low noise figure combined with high gain.

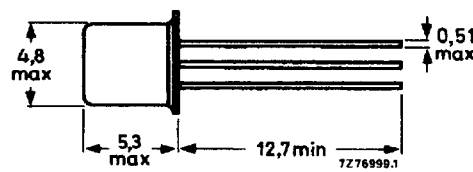
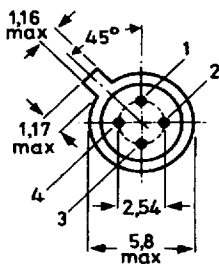
QUICK REFERENCE DATA

Drain-source voltage	V_{DS}	max.	20 V
Drain current	I_D	max.	50 mA
Total power dissipation up to $T_{amb} = 25^\circ\text{C}$	P_{tot}	max.	300 mW
Junction temperature	T_j	max.	175 $^\circ\text{C}$
Transfer admittance at $f = 1\text{ kHz}$ $I_D = 10\text{ mA}; V_{DS} = 10\text{ V}; +V_{G2-S} = 4\text{ V}$	$ y_{fs} $	typ.	15 mS
Input capacitance at gate 1; $f = 1\text{ MHz}$ $I_D = 10\text{ mA}; V_{DS} = 10\text{ V}; +V_{G2-S} = 4\text{ V}$	C_{ig1-s}	typ.	5.5 pF
Feedback capacitance at $f = 1\text{ MHz}$ $I_D = 10\text{ mA}; V_{DS} = 10\text{ V}; +V_{G2-S} = 4\text{ V}$	C_{rs}	typ.	30 fF
Noise figure at optimum source admittance $I_D = 10\text{ mA}; V_{DS} = 10\text{ V}; +V_{G2-S} = 4\text{ V}$ $G_S = 1.2\text{ mA}; -B_S = 5.7\text{ mS}; f = 200\text{ MHz}$	F	typ.	2.3 dB

MECHANICAL DATA

Fig.1 TO-72.

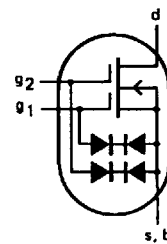
Source and substrate connected to the case.



Dimensions in mm

Pinning:

- 1 = drain
- 2 = gate 2
- 3 = gate 1
- 4 = source



Accessories: 56246 (distance disc).

RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC 134)

Drain-source voltage	V_{DS}	max.	20 V
Drain current (DC or average)	I_D	max.	50 mA
Drain current (peak value)	I_{DM}	max.	100 mA
Gate 1-source current	$\pm I_{G1-S}$	max.	10 mA
Gate 2-source current	$\pm I_{G2-S}$	max.	10 mA
Total power dissipation up to $T_{amb} = 25\text{ }^\circ\text{C}$	P_{tot}	max.	300 mW
Storage temperature range	T_{stg}		-65 to + 175 $^\circ\text{C}$
Junction temperature	T_j	max.	175 $^\circ\text{C}$

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THERMAL RESISTANCE

From junction to ambient in free air	$R_{th\ j-a}$	=	500 K/W
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STATIC CHARACTERISTICS

 $T_j = 25\text{ }^\circ\text{C}$

Gate cut-off currents

$\pm V_{G1-S} = 5\text{ V}; V_{G2-S} = V_{DS} = 0$	$\pm I_{G1-SS}$	max.	10 nA
$\pm V_{G1-S} = 5\text{ V}; V_{G2-S} = V_{DS} = 0; T_j = 150\text{ }^\circ\text{C}$	$\pm I_{G1-SS}$	max.	10 μA
$\pm V_{G2-S} = 5\text{ V}; V_{G1-S} = V_{DS} = 0$	$\pm I_{G2-SS}$	max.	10 nA
$\pm V_{G2-S} = 5\text{ V}; V_{G1-S} = V_{DS} = 0; T_j = 150\text{ }^\circ\text{C}$	$\pm I_{G2-SS}$	max.	10 μA

Gate-source breakdown voltages

$\pm I_{G1-SS} = 0.1\text{ mA}; V_{G2-S} = V_{DS} = 0$	$\pm V_{(BR)G1-SS}$	6 to 20 V
$\pm I_{G2-SS} = 0.1\text{ mA}; V_{G1-S} = V_{DS} = 0$	$\pm V_{(BR)G2-SS}$	6 to 20 V

Drain current

$V_{DS} = 10\text{ V}; V_{G1-S} = 0; +V_{G2-S} = 4\text{ V}$	I_{DSS}	20 to 55 mA
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Gate 1-source voltage

$I_D = 10\text{ mA}; V_{DS} = 10\text{ V}; +V_{G2-S} = 4\text{ V}$	$-V_{G1-SS}$	0.6 to 2.1 V
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Gate-source cut-off voltages

$I_D = 10\text{ }\mu\text{A}; V_{DS} = 10\text{ V}; +V_{G2-S} = 4\text{ V}$	$-V_{(P)G1-S}$	1.5 to 3.8 V
$I_D = 10\text{ }\mu\text{A}; V_{DS} = 10\text{ V}; V_{G1-S} = 0$	$-V_{(P)G2-S}$	1.5 to 3.4 V

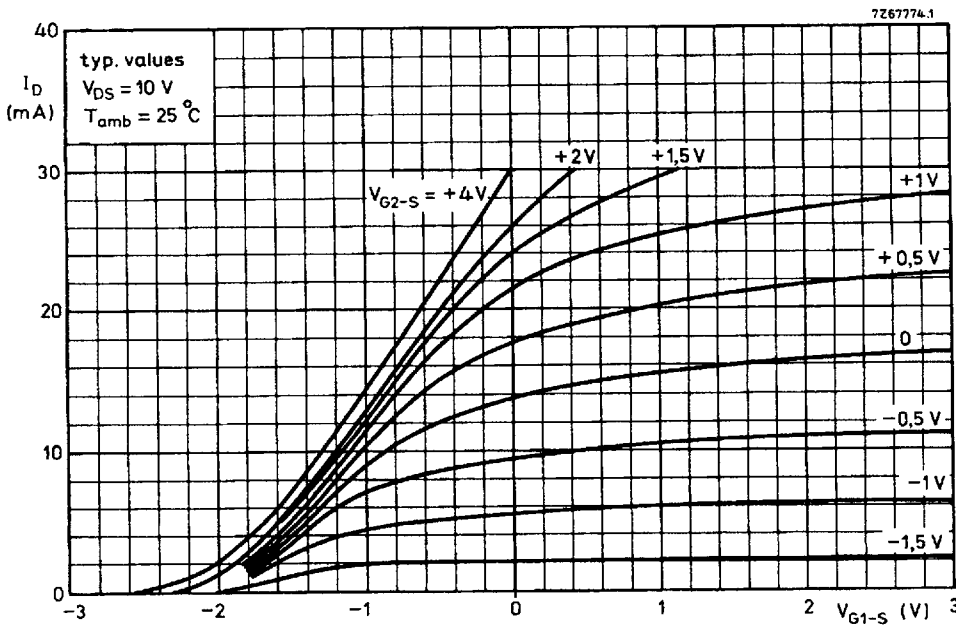
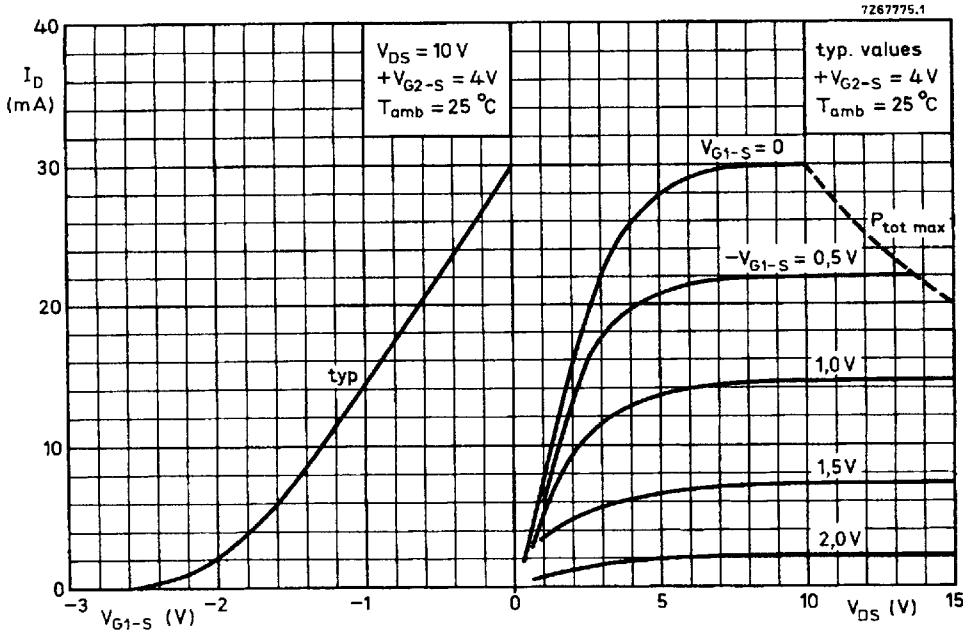
DYNAMIC CHARACTERISTICS

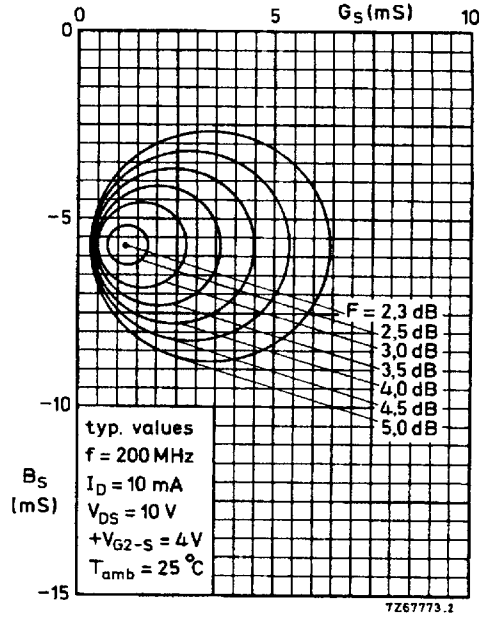
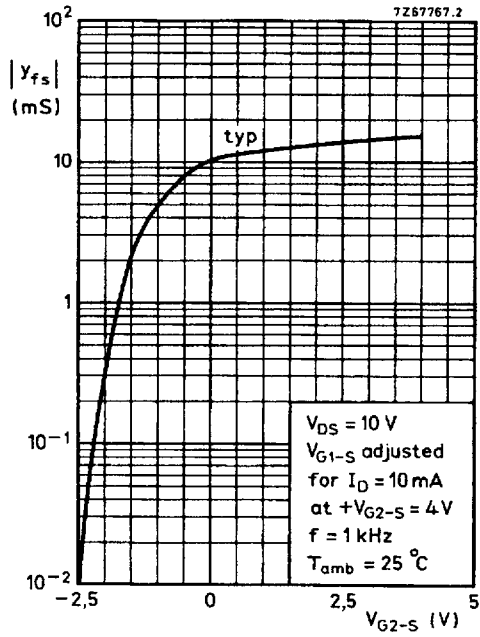
Measuring conditions (common source): $I_D = 10\text{ mA}; V_{DS} = 10\text{ V}; +V_{G2-S} = 4\text{ V}; T_{amb} = 25\text{ }^\circ\text{C}$

Transfer admittance at $f = 1\text{ kHz}$	$ y_{fs} $	min.	12 mS
		typ.	15 mS
Input capacitance at gate 1; $f = 1\text{ MHz}$	C_{ig1-s}	typ.	5.5 pF
Feedback capacitance at $f = 1\text{ MHz}$	C_{rs}	typ.	30 fF
Output capacitance at $f = 1\text{ MHz}$	C_{os}	typ.	3.5 pF
Noise figure at optimum source admittance			
$G_S = 0.95\text{ mS}; -B_S = 5.0\text{ mS}; f = 100\text{ MHz}$	F	typ.	1.9 dB
$G_S = 1.20\text{ mS}; -B_S = 5.7\text{ mS}; f = 200\text{ MHz}$	F	typ.	2.3 dB
		max.	3.0 dB
Cross modulation at $f = 200\text{ MHz}$			
Wanted signal at $f_o = 197.5\text{ MHz}$			
Unwanted signal at $f_{int} = 202.5\text{ MHz}$			
Interference voltage at g_1 for $K = 1\%$	V_{int}	typ.	100 mV (note 1)

Note

1. Cross modulation is defined here as the voltage at g_1 of an unwanted signal with 80% modulation depth, giving 0.8% modulation depth on the wanted signal (a.m. definition).





circles of constant noise figure